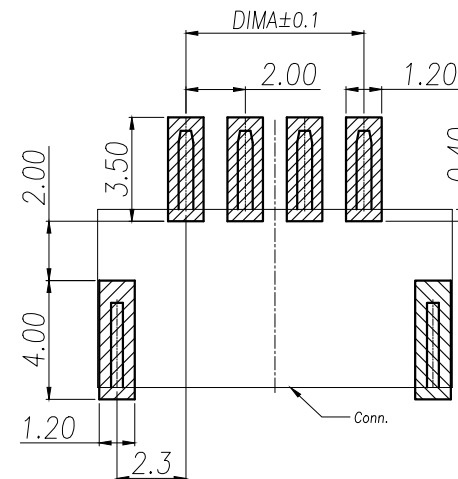
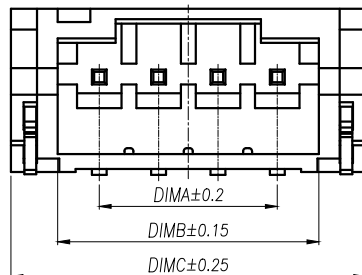
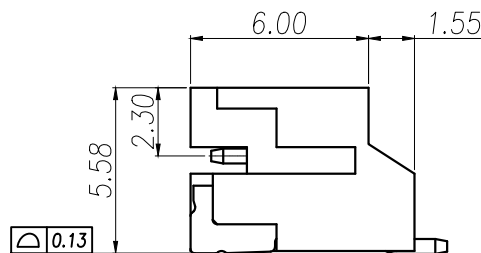
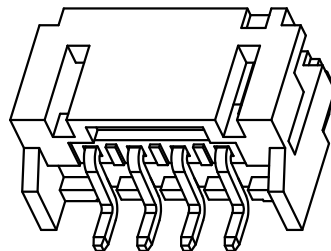
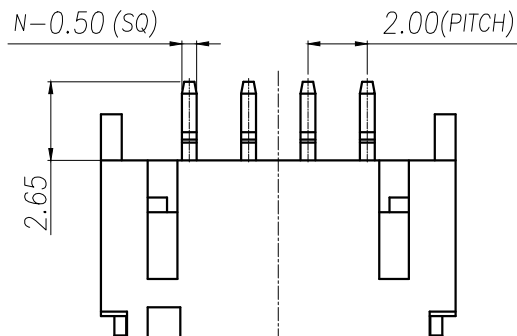


PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)

SMT SOLDER AREA

Part No	PIN	A	B
XY-B2B-PH-K-S	2	2	6
XY-B3B-PH-K-S	3	4	8
XY-B4B-PH-K-S	4	6	10
XY-B5B-PH-K-S	5	8	12
XY-B6B-PH-K-S	6	10	14
XY-B7B-PH-K-S	7	12	16
XY-B8B-PH-K-S	8	14	18
XY-B9B-PH-K-S	9	16	20
XY-B10B-PH-K-S	10	18	22
XY-B11B-PH-K-S	11	20	24
XY-B12B-PH-K-S	12	22	26
XY-B13B-PH-K-S	13	24	28
.....	...	...	...
XY-B20B-PH-K-S	20	(20-1)*2	(20+1)*2

技术要求:

- 1、塑件材料:PA66 (UL-94V-0)
- 2、接触件:黄铜镀锡
- 3、接触电阻: $\leq 10m\Omega$
- 4、绝缘电阻: $\geq 1000M\Omega$
- 5、额定电压:250V AC DC
- 6、额定电流:2.0A AC DC
- 7、耐压:能承受1000V AC/Min ute
- 8、工作温度: $-25^{\circ}\sim +85^{\circ}$
- 9、可焊性试验:浸锡面积 $\geq 95\%$ 温度 $220\pm 5^{\circ}$,时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.35	X.*±5°	APR.	Alex	TITLE: WAFER 2.00mm H5.6mm 90°SMT	
.XX±0.25	.X.*±3°	CHK.	Jack	DWG NO. XY-BNB-PH-K-S	
.XXX±0.15	.XX.*±1°	DRA.	Can	PROJ.	CUSTOMER DRAWING
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A		